Contact Name Title - Contact Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product	IPC - ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
Company name* Company name* Company unique ID Unique ID Authority Response Date* 2024-04-25 Contact Name Title - Contact Title - Contact Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards P	752-21.1										als and Mfg	Informati	ion		
Inter Name Title - Contact Phone - Contact* Phone - Contact* Phone - Contact* Phone - Contact* Product-Env-Stewards Product-Env-Stewards Product Enviro Compliance Phone - Representative* Title - Representative Phone - Representative* Phone - Representative* Phone - Representative* Phone - Representative Phone - Representative Phone - Representative Product-Env-Stewards © onsemi.com Product-Env-Stewards © onsemi.com	upplier Inform	ation						·							
Title - Contact Name Product Envi-Stewards P	Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
Product Enviro Compliance uthorized Representative* Title - Representative Product Enviro Compliance NA Product Env-Stewards @onsemi.com NA Product Enviro Compliance NA Product Enviro Compliance NA Product Enviro Compliance NA Product Enviro Stewards @onsemi.com NA Product Enviro Compliance NA Product Env-Stewards @onsemi.com NA Product Enviro Compliance NA Product Env-Stewards @onsemi.com NA Product Enviro Stewards @onsemi.com NA NA Product Env-Stewards @onsemi.com NA Product Enviro Stewards @onsemi.com NA	onsemi											2024-04-25			
Authorized Representative* Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Effective Date Version Manufacturing Site Weight* UOM UMAnufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Base Alloy Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Base Alloy Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Base	Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Envi- Stewards Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name CPH3362-TL-W PCH 0.7A 100V SOT-23 Description of the product Environt Compliance Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy T	Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*			
CPH3362-TL-W PCH 0.7A 100V SOT-23 2024-04-25 CNG 12.63 mg E Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles contains Bi CU Alloy 1 260 C 30 seconds 3 comments	Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles contains Bi Comments Comments	Requester	r Item Number			Mfr Item Name			Effective Date	Version	N	Manufacturing Site	W	eight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles contains Bi Cu Alloy 1 260 C 30 seconds 3					PCH 0.7A 100V SC	OT-23 20		2024-04-25		C	CNG		2.63	mg	Each
contains Bi CU Alloy 1 260 C 30 seconds 3 comments				orminal Daga	Alloy	STD 020 MSI	Pating	Dook Proc	ooss Pody T	Comporatur	May Time at Peak	Tomporatu	n Numb	per of Poflow Cya	los
omments				•		31D-020 MSL	Kating			Т,				ber of Reflow Cyc	ies
		DI		U Alloy	1			200		IC	30	seconds	5 [3		
ver 1 - maximum ume at peak temperature during soldering is 10-50 seconds		ima at naak tampar-t	duning s-1-	domina ia 10.1	20 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.17	mg	Supplier	Silicon (Si)	7440-21-3		0.17	mg
Die Attach Solder	0.1	mg	Supplier	Silver (Ag)	7440-22-4		0.0025	mg
			A	Lead (Pb)	7439-92-1	7a	0.0925	mg
			Supplier	Tin (Sn)	7440-31-5		0.005	mg
Lead Frame	5.1	mg	Supplier	Silver (Ag)	7440-22-4		0.0556	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0097	mg
			Supplier	Iron (Fe)	7439-89-6		0.1311	mg
			Supplier	Copper (Cu)	7440-50-8		4.8965	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0071	mg
Mold Compound-Black	7.03	mg		Epoxy Phenol Resin	proprietary data		0.0562	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0703	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.4218	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.624	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.8436	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.0141	mg
Plating	0.21	mg	В	Bismuth (Bi)	7440-69-9		0.0013	mg
			Supplier	Tin (Sn)	7440-31-5		0.2087	mg
Wire Bond - Cu	0.02	mg	Supplier	Copper (Cu)	7440-50-8		0.02	mg